

2016 ACM/IEEE International Workshop on System Level Interconnect Prediction (SLIP 2016)

**Austin, Texas, USA
4 June 2016**



**IEEE Catalog Number: CFP16SLP-POD
ISBN: 978-1-5090-3092-7**

**Copyright © 2016, The Association for Computing Machinery (ACM)
All Rights Reserved**

******This publication is a representation of what appears in the IEEE Digital Libraries. Some format issues inherent in the e-media version may also appear in this print version.***

IEEE Catalog Number:	CFP16SLP-POD
ISBN (Print-On-Demand):	978-1-5090-3092-7
ISBN (Online):	978-1-4503-4430-2

Additional Copies of This Publication Are Available From:

Curran Associates, Inc
57 Morehouse Lane
Red Hook, NY 12571 USA
Phone: (845) 758-0400
Fax: (845) 758-2633
E-mail: curran@proceedings.com
Web: www.proceedings.com

CURRAN ASSOCIATES INC.
proceedings
.com

TABLE OF CONTENTS

A Comparative Analysis of Front-End and Back-End Compatible Silicon Photonic On-Chip Interconnects.....	1
<i>I. Thakkar, S. Chittamuru, S. Pasricha</i>	
Latch Clustering for Minimizing Detection-to-Boosting Latency Toward Low-Power Resilient Circuits	9
<i>C.-C. Hsu, M. Lin, M. Hashimoto</i>	
Connectivity Effects on Energy and Area for Neuromorphic System with High Speed Asynchronous Pulse Mode Links.....	15
<i>C. Segal, A. Dalakoti, M. Miller, F. Brewer</i>	
Buffered Interconnects in 3D IC Layout Design	22
<i>M. Ahmed, S. Mohapatra, M. Chrzanowska-Jeske</i>	
Topologically-Geometric Routing	30
<i>R. Bazylevych, M. Palasinski, L. Bazylevych</i>	
Revisiting 3DIC Benefit with Multiple Tiers	36
<i>W.-T. Chan, A. Kahng, J. Li</i>	
Spin-Hall Assisted STT-RAM Design and Discussion	44
<i>E. Eken, I. Bayram, Y. Zhang, B. Yan, W. Wu, H. Li, Y. Chen</i>	
A Demand-Aware Predictive Dynamic Bandwidth Allocation Mechanism for Wireless Network-on-Chip	48
<i>N. Mansoor, M. Shamim, A. Ganguly</i>	
Author Index	